

# APT10026L2FLL

**1000V 38A 0.260**Ω

# POWER MOS 7™

FREDFET

Power MOS  $7^{\text{TM}}$  is a new generation of low loss, high voltage, N-Channel enhancement mode power MOSFETS. Both conduction and switching losses are addressed with Power MOS  $7^{\text{TM}}$  by significantly lowering  $R_{\text{DS(ON)}}$  and  $Q_g$ . Power MOS  $7^{\text{TM}}$  combines lower conduction and switching losses along with exceptionally fast switching speeds inherent with APT's patented metal gate structure.

• Lower Input Capacitance

Increased Power Dissipation

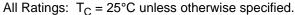
• Lower Miller Capacitance

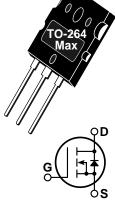
Easier To Drive

Lower Gate Charge, Qg

**MAXIMUM RATINGS** 

Popular TO-264 MAX Package





Symbol	Parameter	APT10026L2FLL	UNIT	
V <sub>DSS</sub>	Drain-Source Voltage	1000	Volts	
I <sub>D</sub>	Continuous Drain Current @ T <sub>C</sub> = 25°C	38	Amne	
I <sub>DM</sub>	Pulsed Drain Current (1)	152	Amps	
V <sub>GS</sub>	Gate-Source Voltage Continuous	±30	Valta	
V <sub>GSM</sub>	Gate-Source Voltage Transient	±40	Volts	
P <sub>D</sub>	Total Power Dissipation @ T <sub>C</sub> = 25°C	890	Watts	
, D	Linear Derating Factor	7.12	W/°C	
$T_J$ , $T_{STG}$	Operating and Storage Junction Temperature Range	-55 to 150	- °C	
T <sub>L</sub>	Lead Temperature: 0.063" from Case for 10 Sec.	300	] ~	
I <sub>AR</sub>	Avalanche Current (1) (Repetitive and Non-Repetitive)	38	Amps	
E <sub>AR</sub>	Repetitive Avalanche Energy 1	50		
E <sub>AS</sub>	Single Pulse Avalanche Energy 4	3200	- mJ	

### STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage $(V_{GS} = 0V, I_D = 250\mu\text{A})$	1000			Volts
I <sub>D(on)</sub>	On State Drain Current $② (V_{DS} > I_{D(on)} \times R_{DS(on)} Max, V_{GS} = 10V)$	38			Amps
R <sub>DS(on)</sub>	Drain-Source On-State Resistance (V <sub>GS</sub> = 10V, 0.5 I <sub>D[Cont.]</sub> )			0.260	Ohms
I <sub>DSS</sub>	Zero Gate Voltage Drain Current (V <sub>DS</sub> = V <sub>DSS</sub> , V <sub>GS</sub> = 0V)			250	μА
	Zero Gate Voltage Drain Current ( $V_{DS} = 0.8 V_{DSS}$ , $V_{GS} = 0V$ , $T_{C} = 125$ °C)			1000	
I <sub>GSS</sub>	Gate-Source Leakage Current $(V_{GS} = \pm 30V, V_{DS} = 0V)$			±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage $(V_{DS} = V_{GS}, I_{D} = 5mA)$	3		5	Volts

CAUTION: These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

APT Website - http://www.advancedpower.com

USA 405 S.W. Columbia Street Bend, Oregon 97702-1035 Phone: (541) 382-8028 FAX: (541) 388-0364 EUROPE Chemin de Magret F-33700 Merignac - France Phone: (33) 5 57 92 15 15 FAX: (33) 5 56 47 97 61

#### **DYNAMIC CHARACTERISTICS**

APT10026L2FLL

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0V		7680		
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 25V		1270		pF
$C_{rss}$	Reverse Transfer Capacitance	f = 1 MHz		252		
$Q_g$	Total Gate Charge <sup>③</sup>	V <sub>GS</sub> = 10V		294		
$Q_{gs}$	Gate-Source Charge	$V_{DD} = 0.5 V_{DSS}$		45		nC
$Q_{gd}$	Gate-Drain ("Miller") Charge	I <sub>D</sub> = I <sub>D</sub> [Cont.] @ 25°C		196		
t <sub>d</sub> (on)	Turn-on Delay Time	V <sub>GS</sub> = 15V		17		
tr	Rise Time	$V_{DD} = 0.5 V_{DSS}$		8		ns
t <sub>d</sub> (off)	Turn-off Delay Time	I <sub>D</sub> = I <sub>D</sub> [Cont.] @ 25°C		39		113
t <sub>f</sub>	Fall Time	$R_G = 0.6\Omega$		9		

## SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Symbol	Characteristic / Test Conditions		MIN	TYP	MAX	UNIT
I <sub>S</sub>	Continuous Source Current (Body Diode)				38 152 Amps	
I <sub>SM</sub>	Pulsed Source Current (Body Diode)					
V <sub>SD</sub>	Diode Forward Voltage ② (V <sub>GS</sub> = 0V, I <sub>S</sub> = -I <sub>D</sub> [Cont.])				1.3	Volts
dv/ <sub>dt</sub>	Peak Diode Recovery dv/dt (5)				18	V/ns
	Reverse Recovery Time	T <sub>j</sub> = 25°C			310	20
t <sub>rr</sub>	$(I_S = -I_D [Cont.], \frac{di}{dt} = 100A/\mu s)$	T <sub>j</sub> = 125°C			625	ns
	Reverse Recovery Charge	T <sub>j</sub> = 25°C		2.0		
$Q_{rr}$	$(I_S = -I_D [Cont.], \frac{di}{dt} = 100A/\mu s)$	T <sub>j</sub> = 125°C		6.0		μC
I <sub>RRM</sub>	Peak Recovery Current	T <sub>j</sub> = 25°C		15		A
	$(I_S = -I_D [Cont.], \frac{di}{dt} = 100A/\mu s)$	T <sub>j</sub> = 125°C		2.6		Amps

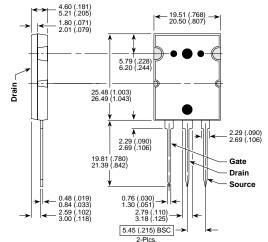
#### THERMAL CHARACTERISTICS

Symbol	Characteristic	MIN	TYP	MAX	UNIT
$R_{ hetaJC}$	Junction to Case			0.14	
$R_{\theta,IA}$	Junction to Ambient			40	°C/W

① Repetitive Rating: Pulse width limited by maximum junction temperature.

APT Reserves the right to change, without notice, the specifications and information contained herein.

### TO-264 MAX™(L2) Package Outline



Dimensions in Millimeters and (Inches)

② Pulse Test: Pulse width < 380 µs, Duty Cycle < 2%

③ See MIL-STD-750 Method 3471

 $<sup>\</sup>bigcirc$  Starting T<sub>j</sub> = +25°C, L = 4.43mH, R<sub>G</sub> = 25Ω, Peak I<sub>L</sub> = 38A

<sup>(5)</sup>  $dv/_{dt}$  numbers reflect the limitations of the test circuit rather than the device itself.  $I_S \le -I_{D[Cont.]}$   $di/_{dt} \le 700A/\mu s$   $V_R \le V_{DSS}$   $T_J \le 150^{\circ}C$